

LISTING OF THE CLAIMS

This listing of claims, amended as indicated below, replaces all prior versions, and listings, of claims in the application

1. (Canceled)

2. (Currently Amended) A method as claimed in claim [[1]] 21, including extending the wire from the second bump ball.

3. (Currently Amended) A method as claimed in claim [[1]] 21, wherein the second bump ball partially lies on the connection pad and partially lies on the first bump ball.

4. (Currently Amended) A method as claimed in claim [[1]] 21, including severing the wire from the first bump ball prior to forming the second bump ball.

5. (Canceled)

6. (Currently Amended) A method as claimed in claim [[5]] 21, wherein the second bump ball is formed on the recessed portion of the first bump ball.

7. (Canceled)

8. (Currently Amended) A method as claimed in claim [[7]] 22, including extending the wire from the additional bump ball.

9. (Currently Amended) A method as claimed in claim 7, including severing the wire from the second bump ball prior to forming the additional bump ball.

10. (Canceled)

11. (Currently Amended) A method as claimed in claim [[9]] 22, wherein the additional bump ball is formed on the recessed portion of the first or second bump ball.

12. (Currently Amended) A method as claimed in claim [[1]] 21, wherein the diameter of the wire is less than 50 μ m.

13-20: (Canceled).

21. (New) A method of forming a wire bond bonding a wire to a connection pad of an electronic device comprising the steps of:
forming a first bump ball on the connection pad;
edging the first bump ball and forming a recessed portion in the bump ball; and then
forming a second bump ball on the connection pad that is contiguous with the first bump ball.

22. (New) A method of forming a wire bond bonding a wire to a connection pad of an electronic device comprising the steps of:
forming a first bump ball on the connection pad;
forming a second bump ball on the connection pad that is contiguous with the first bump ball;
edging the first and/or second bump ball and forming a recessed portion in the first and/or second bump ball; and then
forming an additional bump ball that is contiguous with the first and/or second bump ball.

23. (New) A wire bond formed according to the method of claim 21.

24. (New) An electronic device including wire bonds as claimed in claim 23.